



MEGIC-01-013B

January 14, 2004

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/690,350 10/21/03

Mou-Shiung Lin et al.

THIN FILM SEMICONDUCTOR PACKAGE
AND METHOD OF FABRICATION

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 1/27/04

The following two publications relate to the use of thin

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films in the interconnection and packaging of semiconductor dies:

- 1) Microelectronic Packaging Handbook, Chapter 9, R.R. Tummala et al., Van Nostrand Reinhold, NY, 1989, pp. 673-725.
- 2) Novel Microelectronic Packaging Method for Reduced Thermomechanical Stresses on Low Dielectric Constant Materials, R.M. Emery et al., Intel Corp., Chandler, AZ.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

Application Number:

10/690,350

Mou-Shiung Lin et al.

10/24/03

Group Art Unit

O I P E J C 2 6
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(Use several sheets if necessary)

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Translation

YES

NO

OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)

- Microelectronic Packaging Handbook, Chapter 9, R.R. Tummala et al., Van Nostrand Reinhold, NY, 1989, pp. 673-725.

- Novel Microelectronic Packaging Method for Reduced Thermomechanical Stresses on Low Dielectric Constant Materials, R.M. Emery, et al., Intel Corp., Chandler, AZ.

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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.